

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Hak-Lay CHUANG	05/23/2011
Ming ZHU	05/23/2011
Lee-Wee TEO	05/23/2011
Bao-Ru YOUNG	05/23/2011
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13115488
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	2011-0103/24061.1783
NAME OF SUBMITTER:	David M. O'Dell
Total Attachments: 3 source=1783_Assignment#page1.tif source=1783_Assignment#page2.tif source=1783_Assignment#page3.tif	

OP \$40.00 13115488

Docket No.: 2011-0103 / 24061.1783
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

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|-----|----------------|----|---|
| (1) | Hak-Lay Chuang | of | No. 59, Alley 18, Lane 85, Guqun Street, Townshipshan District Hsinchu City 300, Taiwan, R.O.C. |
| (2) | Ming Zhu | of | Block 688F, #13-74, Woodlands Drive 75 Singapore 736688 |
| (3) | Lee-Wee Teo | of | 607, Senja Road, #10-06 Singapore 670607 |
| (4) | Bao-Ru Young | of | No. 7, Lane 1, Liujia 2nd Street Zhubei City, Hsinchu County 302, Taiwan, R.O.C. |

have invented certain improvements in

A SEMICONDUCTOR STRUCTURE WITH SUPPRESSED STI DISHING EFFECT AT RESISTOR REGION

for which we have executed an application for Letters Patent of the United States of America, filed on May 25, 2011 and assigned application number 13/115,488; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and

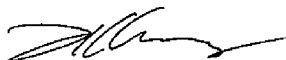
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testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Hak-Lay Chuang

Residence Address: No. 59, Alley 18, Lane 85, Guqun Street, Townshipshan District
Hsinchu City 300, Taiwan, R.O.C.

Dated: 23 May, 2011

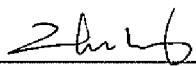


Inventor Signature

Inventor Name: Ming Zhu

Residence Address: Block 688F, #13-74, Woodlands Drive 75
Singapore 736688

Dated: 23 May - 2011

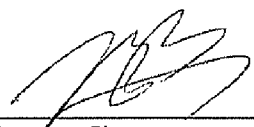


Inventor Signature

Inventor Name: Lee-Wee Teo

Residence Address: 607, Senja Road, #10-06
Singapore 670607

Dated: 23 May 2011



Inventor Signature

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Inventor Name: Bao-Ru Young

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Zhubei City, Hsinchu County 302, Taiwan, R.O.C.

Dated: 2011/05/23

BRYoung
Inventor Signature
